Special Issue

Trends and Recent Advancements in Structural Health Monitoring

Message from the Guest Editors

This call for papers welcomes manuscripts dealing with recent advancements in the fields of SHM that cover material characterizations and structural components, with a specific focus on additively manufactured components. We invite researchers to submit their related work on any types of sensors (contact and noncontact) applied to SHM systems, innovative research, and reviews. The topics include, but are not limited to:

- Wired and wireless sensing for SHM
- In situ contact and non-contact sensors in additive manufacturing
- Sensor integration/embedment during manufacturing
- Feature extraction and data fusion of sensor networks
- Damage localization and assessment in additively manufactured systems

Guest Editors

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Prof. Dr. Pawel H. Malinowski

Dr. Samir Mustapha

Deadline for manuscript submissions

closed (10 January 2024)



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Message from the Editor-in-Chief

You are invited to contribute either a research article or a comprehensive review for consideration and publication in *Processes* (ISSN 2227-9717). *Processes* is published in open access format – research articles, reviews, and other content are released on the internet immediately after acceptance. The scientific community and the general public have unlimited, free access to the content. As an open access journal, *Processes* is supported by the authors and their institutes through the payment of article processing charges (APCs) for accepted papers. We would be pleased to welcome you as one of our authors.

Editor-in-Chief

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